

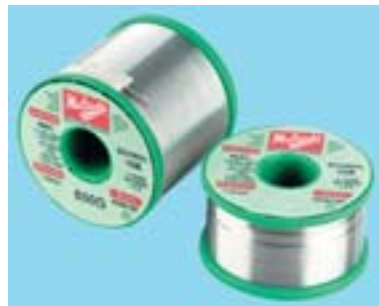
Solder - Lead Free - continued

Lead Free (99C) Alloy, X39 No-Clean Flux - continued

339065.344682

Weight	Wire Diameter	Order Code	Price Per Reel	
			1+	10+
250g Reels	0.5mm	509-0945	1,150.00	1,045.00
	0.7mm	509-0957	850.00	772.00
	0.9mm	509-0969	830.00	754.00
500g Reels	0.7mm	509-0994	1,561.00	1,419.00
	0.9mm	509-1007	1,514.00	1,376.00
	1.2mm	509-1019	1,462.00	1,328.00

Lead Free (99C) Alloy, 502 No-Clean Flux



- Mildly activated (0.2%) flux formulation
- Increased flux content (3% by weight) - low fuming and low spitting
- Minimal clear residues no not require cleaning
- Complies with all lead-free legislative requirements
- Suitable for general lead-free, no-clean assembly, or rework of PCBs assembled in a lead-free no-clean process

Alloy Lead Free, 99.3% Tin, 0.7% Copper Alloy Melting Temperature 227°C
 Flux Type Mildly Activated (0.2%) formulation, No clean Tip Temperature (Approx.) 350°C - 370°C

339067.344683

Weight	Wire Diameter	Order Code	Price Per Reel	
			1+	10+
250g Reels	0.5mm	509-1020	963.00	875.00
	0.7mm	509-1032	825.00	750.00
	0.9mm	509-1044	799.00	726.00
500g Reels	0.7mm	509-1070	1,594.00	1,450.00
	0.9mm	509-1081	1,547.00	1,406.00
	1.2mm	509-1093	1,497.00	1,361.00

LF320 Lead Free No-Clean Solder Paste



- General purpose for stencil printing applications
- Wide printing and reflow process windows (air and nitrogen)
- Good tack performance, excellent slump resistance
- 96SC (SAC Alloy)
- No-clean, residues
- 88% metal content
- IPC/J-STD ROMO approved

Alloy 96SC (SAC Alloy), 95.5% Tin, 3.5% Silver, 0.7% Copper, 217°C Liquidus

339071

Size	Mfrs. List No.	Order Code	Price Each	
			1+	10+
500g	3209885-M	509-1100	10,143.00	9,502.00

Lead Free 96SC Alloy, Colophony Free (105) Flux



- Lead free alloy combined with 105 Colophony-free flux
- Colophony free fully synthetic flux (no rosin or modified rosin) - non corrosive formulation
- High activity - fast and sustained soldering on copper and brass
- Distinctive low odour to distinguish from rosin products
- 95.5% Tin (Sn), 3.5% Silver (Ag), 0.7% Copper (Cu) Alloy
- 217°C melting point (tip temperature of 350°C to 370°C)
- Complies with HSE colophony-free recommendations and all lead-free legislative requirements

- Suitable for general assembly, or rework processes - operationally and aesthetically similar to traditional rosin fluxes

339833/436437

Wire Diameter	Weight	Order Code	Price Per Reel		
			1+	10+	50+
0.7mm	250g	454-590	1,466.00	1,380.00	1,310.00
1mm	250g	454-412	1,423.00	1,233.00	1,171.00

RP11 Lead Free No-Clean Solder Paste

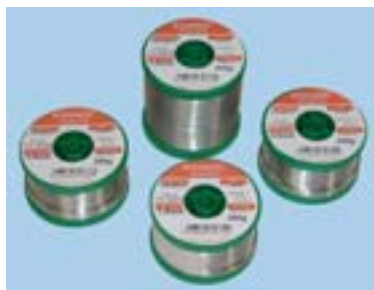


- High activity rosin-based solder paste
- Rosinous (amber) residues do-not need cleaning
- Good tack performance and printer open time
- 96SC (SAC Alloy) 95.5% Tin(Sn), 3.5% Silver(Ag) 0.7% Copper(Cu), 217°C liquidus)
- 90% metal content for stencilling, 250g jars
- Suitable for reflow in air or nitrogen

339835

Size	Order Code	Price Each		
		1+	10+	50+
250g Jar	453-560	5,138.00	4,591.00	3,901.00

Lead Free Solder Wire Alloy TC



- Sn99Cu1
- Proven in electronic manufacturing
- Favourable price (no silver)
- Eutectic alloy (exact melting point 227°C)
- Improved wetting
- Flux type 1.1.2. to EN 29454-1 (F-SW26)

378329

Wire Ø (mm)	Weight (g)	Order Code	Price per Reel		
			1+	5+	10+
1.0	250	840-0369	565.00	506.00	460.00
1.0	500	840-0377	1,057.00	951.00	864.00
1.5	250	840-0385	554.00	498.00	453.00
2.0	250	840-0393	550.00	493.00	448.00

Lead Free Alloy, Rosin Flux

New alloy: Tin (97.1%), Silver (2.6%), Copper (0.3%)



- Lead free
- Contains one core of rosin based flux
- Amber coloured (rosin) residues do not require cleaning
- For all general purpose lead-free electronic assembly and re-work applications



- Complies with all lead-free legislative requirements

Alloy Sn97.1Ag2.6Cu0.3 Tip Temperature (Approx.) 350°C
 Melting Temperature 217°C - 224°C

416044

Weight	Wire Diameter	Order Code	Price Per Reel	
			1+	5+
250g Reels	0.5mm	101-5443	1,508.00	1,358.00
	0.7mm	101-5444	1,090.00	981.00
	1mm	101-5445	978.00	880.00
500g Reels	1.2mm	101-5446	974.00	875.00
	0.7mm	101-5447	2,106.00	1,895.00
	1mm	101-5449	1,882.00	1,694.00
	1.2mm	101-5451	1,873.00	1,686.00

Lead Free Alloy, No-Clean Flux

New alloy: Tin (97.1%), Silver (2.6%), Copper (0.3%)



- Halide free flux formulation
- Contains 5 cores of flux
- Non-corrosive reliable flux residues
- Minimal clear residues do not require cleaning
- Complies with all lead-free legislative requirements



- Suitable for high reliability, lead-free, no-clean assembly, or rework of PCBs assembled in a lead-free no-clean process

Alloy Sn97.1Ag2.6Cu0.3 Tip Temperature (Approx.) 350°C
 Melting Temperature 217°C - 224°C

416047